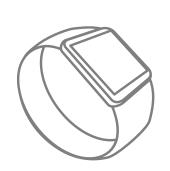
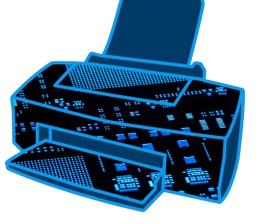
Inkjet Printer

Solution Proposal by Toshiba













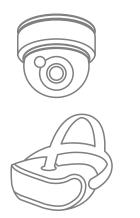








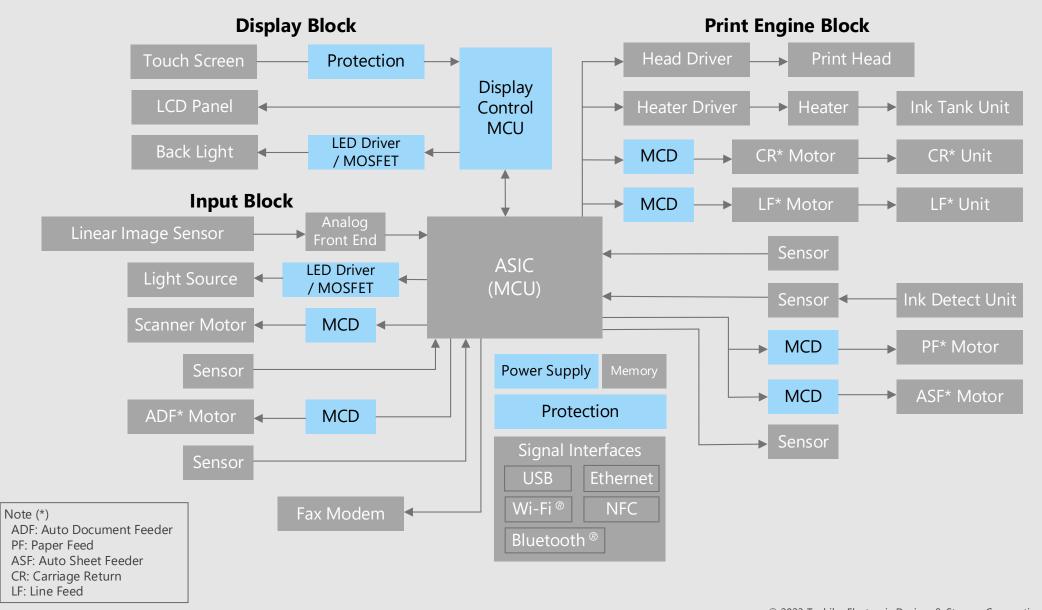
Toshiba Electronic Devices & Storage Corporation provides comprehensive device solutions to customers developing new products by applying its thorough understanding of the systems acquired through the analysis of basic product designs.



Block Diagram

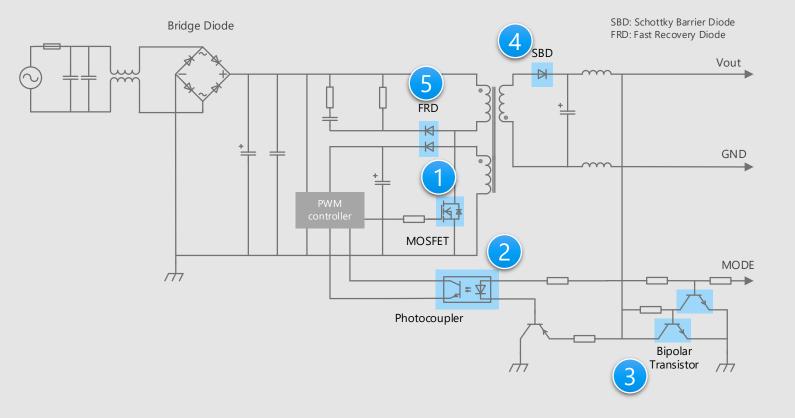
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Inkjet Printer Overall block diagram



Inkjet Printer Detail of the power supply circuit

Power supply circuit



* Click the number in the circuit diagram to jump to the detailed description page

Criteria for device selection

- Transistor output photocoupler is suitable for isolation of feedback signal from the secondary side.
- By using a MOSFET with low on-resistance and high heat dissipation efficiency, a set having low heat generation and low power consumption is realized.
- Small package products contribute to the reduction of circuit board area.

Proposals from Toshiba

Suitable for high efficiency power supply switching
 π-MOS Series MOSFET

Photocoupler with excellent environmental resistance

Transistor output photocoupler

For high speed switching and compact surface mounting

Bipolar transistor

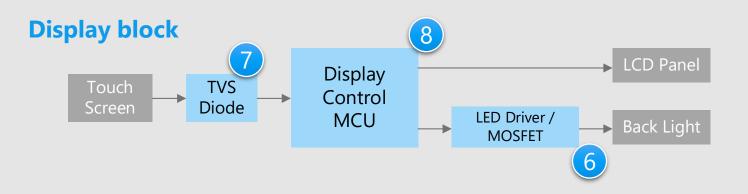
 High speed, low loss Schottky barrier diode

High reverse voltage and short reverse recovery time

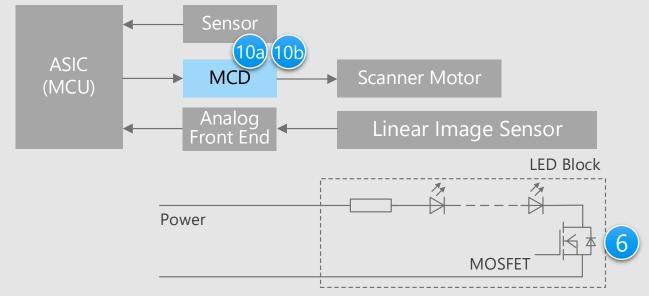
Fast recovery diode



Inkjet Printer Detail of display / scanner block



Scanner block



* Click the number in the circuit diagram to jump to the detailed description page

Criteria for device selection

- Small package products contribute to the reduction of circuit board area.
- TVS diodes are suitable for absorbing the static electricity from external terminals to prevent circuit malfunction and device breakdown.
- Document scanning requires fine control of the light source.

Proposals from Toshiba

- Realizes low on-resistance and low power consumption set Small signal MOSFET
- High speed signal line protection with low capacitance characteristics TVS diode
- All in one chip with a built-in LCD driver MCU TMPM061FWFG
- High precision current control for a scanner Stepping motor driver

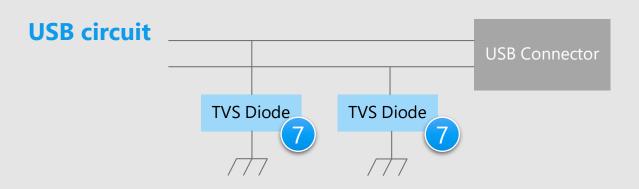








Inkjet Printer Detail of USB / ADF block



ADF block



* Click the number in the circuit diagram to jump to the detailed description page

Criteria for device selection

- Small package products contribute to the reduction of circuit board area.
- TVS diodes are suitable for absorbing the static electricity from external terminals to prevent circuit malfunction and device breakdown.
- Document feeding requires fine control.

Proposals from Toshiba

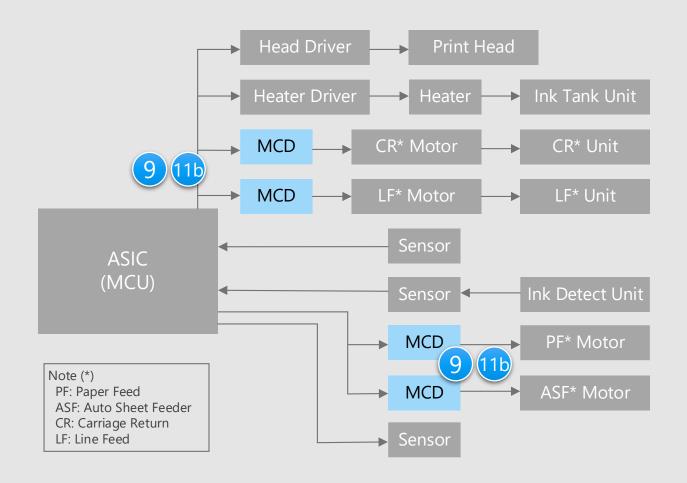
- High speed signal line protection with low capacitance characteristics
 TVS diode
- High precision current control for ADF
 Stepping motor driver
 Brushed DC motor driver





Inkjet Printer Detail of print engine block

Print engine block



* Click the number in the circuit diagram to jump to the detailed description page

Criteria for device selection

Feeding printing a document and a paper requires high precision paper position control.

Proposals from Toshiba

Positioning sorter and sheet with high accuracy



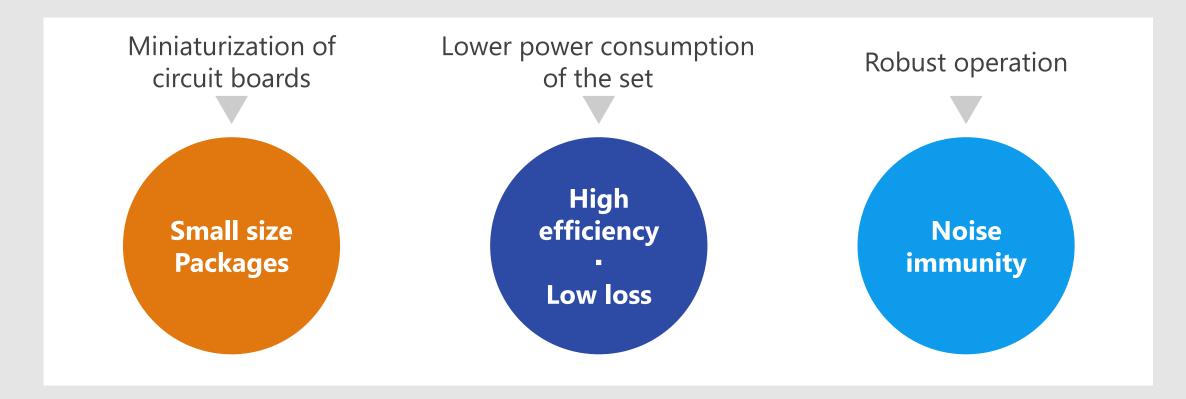






Device solutions to address customer needs

As described above, in the design of Inkjet Printer, "Miniaturization of circuit boards", "Low power consumption of set" and "Robust operation" are important factors. Toshiba's proposals are based on these three solution perspectives.



Device solutions to address customer needs

	Small size Packages	High efficiency Low loss	Noise immunity
1 π-MOS Series MOSFET			
2 Transistor output photocoupler			
3 Bipolar transistor			
4 Schottky barrier diode			
5 Fast recovery diode			
6 Small signal MOSFET			
7 TVS diode			
8 MCU TMPM061FWFG			
Stepping motor driver with a built-in A	AGC		
100 100 Stepping motor driver			
113 11b Brushed DC motor driver			







This MOSFET is suitable for switching regulators and is easy to handle and contributes to miniaturization.

Low on-resistance

By keeping the on-resistance between the drain and source low, heat generation and power consumption can be kept low.

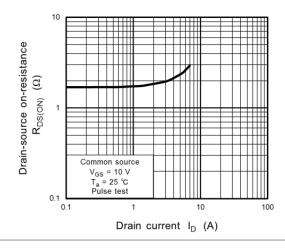
2 Low leakage current

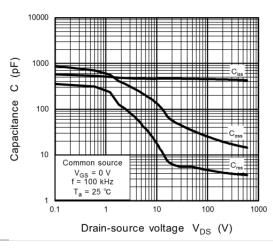
Drain cut-off current $I_{DSS} = 10 \mu A$ (Max) $(V_{DS} = 600 \text{ V})$

3 Enhancement type

It is easy to handle because it is an enhancement type in which no collector current flows when no gate voltage is applied.

TK2K2A60F Characteristics Curves





Lineup						
Part n	umber	TK2K2A60F				
Package		TO-220SIS				
V _{DSS}	_s [V]	600				
	[A]	3.5				
C _{iss} (Ty	p.) [pF]	450				
D [O]	Тур.	1.82				
$R_{DS(ON)}[\Omega]$	Max	2.2				
Polarity		N-ch				







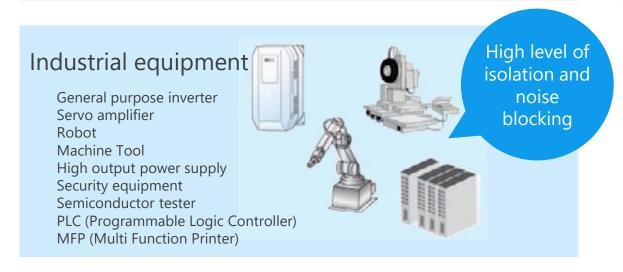
Reduction in required circuit board area and improving reliability enabling maintenance-free operation.

High isolation voltage is realized even using compact and thin package

It is a highly isolated photocoupler that phototransistors and infrared light emitting diodes are optically coupled, and achieved a high isolation voltage of 5000 Vrms. In addition, since the SO6L package is smaller and thinner than Toshiba standard DIP package, high density mounting is possible.

Operating temperature is expanded to 110 °C or 125 °C

It is designed to operate even under severe ambient temperature conditions, such as inverters, robots, machinery and high output power supplies.



Lineup						
Part number	TLP383	TLP385	TLP387	TLP388		
Package	4pin SO6L					
V _{CEO} [V]	80	80	300	350		
BV _S [Vrms]	5000 5000 5000					
T _{opr} [°C]	-55 to 125	-55 to 110	-55 to 110	-55 to 125		







It is suitable for low frequency and low noise applications and covers a wide range of applications.

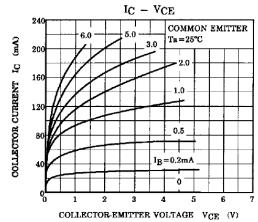
High voltage

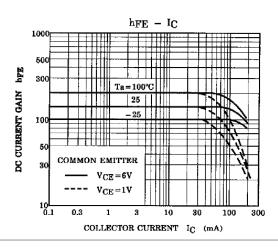
High voltage allows for large loads and instantaneous voltage changes.

Large current (rated collector current)

It covers a wide range of applications, from low frequency applications to power supply applications.

TMBT3904 Characteristics chart





Lineup					
Part number	TMBT3904				
Package	SOT23				
V _{CEO} [V]	50				
I _C [mA]	200				
V _{CE(sat)} (Max) [V]	0.3 @I _C = 50 mA, I _B = 5 mA				
h _{FE}	100 to 300 @V _{CE} =1 V, I _C = 10 mA				
Polarity	NPN				







It is suitable for high frequency rectification of switching power supplies and contributes to miniaturization.

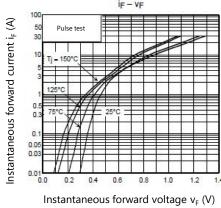
High speed switching

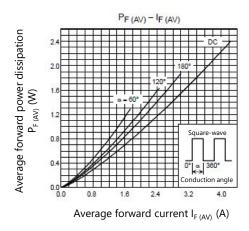
It is suitable for high speed switching applications.

2 Small package

This small package is suitable for high density mounting.

CMS15 Characteristics chart





Lineup		
Part number	CMS15	CUHS20F60
Package	M-FLAT TM	US2H
V _{RRM} / V _R [V]	60	60
I _{F(AV)} / I _O [A]	3.0	2.0
V _{FM} / V _F (Max) [V]	0.58 @I _{FM} = 3.0 A	0.59 @I _F = 2.0 A
C _j (Typ.) [pF]	102	300

5 Fast recovery diode







Value provided

This is a silicon diffusion matching type high frequency rectifier diode. Contributes to high efficiency and miniaturization of power supplies.

High reverse voltage

Repetitive peak reverse voltage (V_{RRM}) is high.

(CRF03A: Rated 600 V)

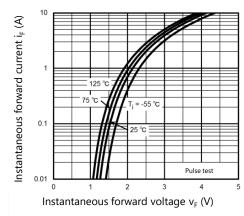
Fast reverse recovery time

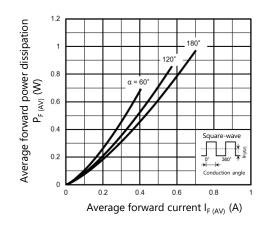
The reverse recovery time (trr) is fast and is suitable for high speed operation. (CRF03A: Up to 100 ns)

3 Small package

This small package is suitable for high density mounting.

CRF03A Characteristics chart





Lineup					
Part number	CRF03A				
Package	S-FLAT TM				
V _{RRM} [V]	600				
I _{F(AV)} [A]	0.7				
V _{FM} (Max) [V]	2.0 @I _{FM} = 0.7 A				
I _{RRM} (Max) [μA]	50				







It is suitable for high speed switches and contributes to miniaturization.

Low voltage operation

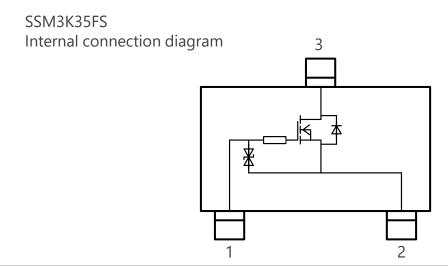
Operate down to $|V_{GS}| = 1.2 \text{ V}$.

DescriptionLow on-resistance

By keeping the on-resistance between the drain and source low, heat generation and power consumption can be kept low.

3 Wide package lineup

In addition to SSM packages, we have CST3C packages, VESM packages, ES6 packages and US6 packages.



Lineup					
Part number		SSM3K35FS	SSM3K35AFS	SSM3J35FS	SSM3J35AFS
Package		SSM 💮	SSM 🗼	SSM 🗼	SSM 🗼
V _{DSS} [V]		20	20	-20	-20
I _D [A]		0.18	0.25	-0.1	-0.25
$R_{DS(ON)}[\Omega]$	Тур.	2	1.1	5.6	1.5
$R_{DS(ON)} [\Omega]$ @ V_{GS} = 2.5 V	Max	4	1.6	11	2.1
Polarity		N-ch	N-ch	P-ch	P-ch







This absorbs static electricity from external terminals, prevents circuit malfunction and protects devices.

Improved ESD pulse absorption

We have improved the absorbency of ESD compared to Toshiba conventional products (50 % reduction in operating resistance). It achieves both low operating resistance and low capacitance, and ensures high signal protection performance and signal quality.

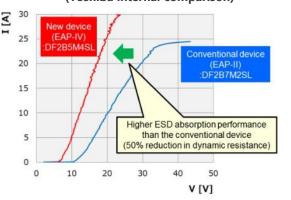
Suppress ESD energy by low clamp voltage

TVS diodes protect connected circuits and devices by adopting proprietary technology.

Suitable for high density mounting

Small size package is suitable for high density mounting.

ESD Pulse Absorption Performance (Toshiba internal comparison)



Unidirectional



Suitable for paths such as logic signals. There is lineups of 1in1, 2in1, 4in1, 5in1, 7in1.

Bidirectional



Suitable for paths with both polar signals such as audio signals

Lineup					
Part number	DF2B5M4ASL	DF2B6M4ASL	DF2B6USL	DF6D6UFE	DF2B6M4BSL
Package	SL2	SL2	SL2	ES6	SL2
V _{ESD} [kV]	±16	±15	±10	±10	±8
V _{RWM} (Max) [V]	3.6	5.5	5.5	5.5	5.5
C _t (Typ.) [pF]	0.15	0.15	1.5	1.5	0.12
R_{DYN} (Typ.) [Ω]	0.7	0.7	0.25	0.25	1.05

(NOTE) This product is an ESD protection diode and cannot be used for purposes other than ESD protection.





System cost down, high efficiency system, development efficiency improvement

Built-in Arm® Cortex®-M0 CPU core

Built-in Arm Cortex-M0 core with Thumb ® instruction set improves energy efficiency. Various development tool and their partners allow users many options.

Suitable for sensing analog signal

Built-in multichannel AD converter and CPU system executes sensing data processing efficiently at low cost.

Small package and low power consumption

Cortex-M0 and original NANOFLASH™ technology bring to the small package and low power consumption. They contribute to reduction of board area and power consumption.

TMPM061FWFG



Package: LQFP100-P-1414-0.50G

Lineup

Part number	TMPM061FWFG
Maximum operation frequency	16 MHz
Instruction ROM	128 KB
RAM	8 KB
Timer	9ch
UART/SIO	4ch
AD converter	2ch (10bit), 3ch (24bit)
LCDD	40 seg x 4 com





Motor current is optimized in real time by using built-in AGC (Active Gain Control).

High voltage (50 V)

The maximum rated voltage of these products is 50 V, it can be used in a supply of 12 to 36 V with sufficient margin.

Step-out prevention and high efficiency control using AGC

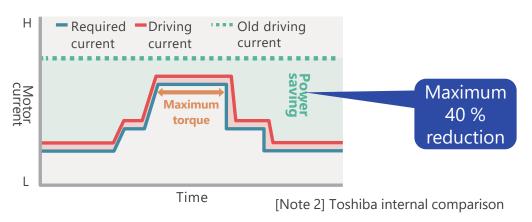
By detecting the motor load torque with just the driver IC and automatically optimizing the current according to the drive condition, step-out avoidance and highly efficient motor control are possible.

ADMD (Advanced Dynamic Mixed Decay) realizes higherficiency operation at high rpm.

Toshiba's original ADMD technology tracks input current more closely than the conventional mixed decay mode [Note 1], making highly efficient motor control possible at high rpm.

[Note 1] Comparison with our products

Active Gain Control



Lineup				
Pa	rt number	TB67S128FTG	TB67S289FTG	
Absolute	Output voltage [V]	50		
maximum ratings	Output current [A]	5.0	3.0	
Output ON-re	sistance (H+L) (Typ.) [Ω]	0.25	0.4	
Cont	trol interface	Clock / Serial	Clock	
	Step	1/1, 1/2,1/4, 1/8, 1/16, 1/32, 1/64, 1/128	1/1, 1/2, 1/4, 1/8, 1/16, 1/32	
	Features ADMD (high efficiency control)		ACDS (without current sense resistor)	
Error detection function		Thermal shutdown (TSD), over current d motor load open (OPD)	etection (ISD), power-on-reset (POR),	
	Package	P-VQFN64-0909-0.50-006	P-VQFN48-0707-0.50-004	







The maximum voltage rating of 40 V. Standard stepping motor drivers with a small package

High voltage and current

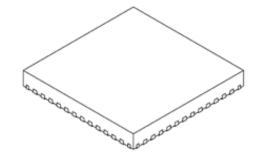
The maximum rated voltage of these products is 40 V, and the maximum rated current is 2 or 2.8 A. Low on-resistance contributes low power consumption and low heat.

2 Small size and high heat dissipation

The package uses a high heat dissipation QFN with an E-Pad on the bottom. Heat is dissipated by connecting the E-Pad part to the board GND. It also contributes to the reduction of board area.

3 Error detection functions

Over current detection (ISD), thermal shutdown (TSD) and power on reset (POR) are available for safe motor driving.



Package: P-WQFN36-0606-0.50-002 (6 x 6 mm)

Lineup					
Part number		TB67S511FTAG	TB67S512FTAG	TB67S521FTAG	TB67S522FTAG
Absolute	Output voltage [V]	40			
maximum ratings	Output current [A]	2	2.0		.8
Output ON-resistance (H+L) (Typ.) [Ω] Driving type Excitation mode		0.8		0.53	
		PWM constant current drive			
		full, half and quarter step resolutions			S
Control interface		Phase	Phase Clock Phase Clock		Clock
Error detection function		Thermal shut down (TSD), over current (ISD), power on reset (POR)			
F	Package		P-WQFN36-0	606-0.50-002	







The maximum voltage rating of 40 V. Standard stepping motor drivers with a small package

High voltage and current

The maximum rated voltage of these products is 40 V, and the maximum rated current is 2 or 1.5 A. Low on-resistance contributes low power consumption and low heat.

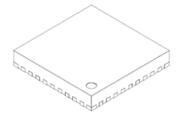
2 Small size and high heat dissipation

The package uses a high heat dissipation QFN with an E-Pad on the bottom. Heat is dissipated by connecting the E-Pad part to the board GND. It also contributes to the reduction of board area.

3 Error detection functions

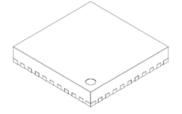
Over current detection (ISD), thermal shut down (TSD) and under voltage lockout (UVLO) are available for safe motor driving.

TB67S539FTG



Package: P-VQFN32-0505-0.50-004 (5 x 5 mm)

TB67S549FTG



Package: P-VQFN24-0404-0.50-004 (4 x 4 mm)

	Lineup				
	Part number		TB67S539FTG	TB67S549FTG	
	Absolute	Output voltage [V]	40	40	
	maxımum ratings	Output current [A]	2.0	1.5	
	Output ON-resistance (H+L) (Typ.) [\Omega] Driving type Excitation mode Control interface Error detection function Package		0.8	1.2	
			PWM constant current drive		
			full, half, quarter, 1/8, 1/16 and 1/32 step resolutions		
			Clock		
			Thermal shut down (TSD), over current (ISD), low voltage (UVLO)		
			Package P-VQFN32-0505-0.50-004 P-VQFN24-0404-0.50-0		P-VQFN24-0404-0.50-004







High voltage, high current and low power consumption with BiCD process. Simple single channel version.

High voltage (50 V)/
High current

Maximum rating of the output voltage is improved from 40 to 50 V to allow margin for air discharge test, etc.

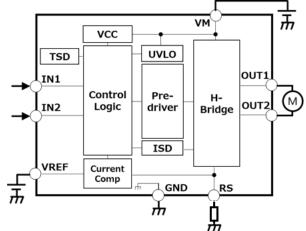
Wide operation voltage range

Wide power supply voltage range from 4.5 to 44 V supports battery driven applications.

3 Mature package

Adopting HSOP8 package compatible with competitor's products or Toshiba conventional products.

■Simple solution





P-HSOP8-0405-1.27-002 (4.9 x 6.0 mm)

Lineup						
Part number		TB67H450AFNG	TB67H451AFNG			
Motor type		Brushed DC motor				
Absolute maximum ratings	Output voltage [V]	50				
	Output current [A]	3.5				
Output ON-resistance (H+L) (Typ.) [Ω]		0.6				
Output circuit		1ch				
Error detection function		Thermal shut down (TSD), over current (ISD), low voltage (UVLO)				
Package		P-HSOP8-0405-1.27-002				







High voltage, high current with BiCD process. More selection supports higher current driving.

High voltage (50 V)/ High current

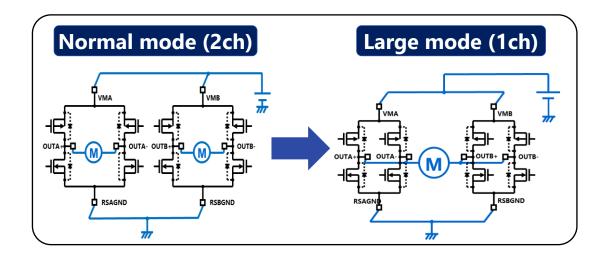
Maximum rating of the output voltage is improved from 40 to 50 V to allow margin for air discharge test, etc.

Wide operation voltage range

Wide operation voltage range from 10 to 47 V supports battery driven applications.

3 High current drive

Built-in 2ch of H-bridge circuit can drive two brushed DC motors or a single brushed motor by using large mode which obtains two times current.



Lineup							
Part number		TB67H400AFTG	TB67H410FTG	TB67H420FTG			
Motor type		Brushed DC motor					
Absolute maximum ratings	Output voltage [V]	50					
	Output current (Normal) [A]	4.0	2.5	4.5			
	Output current (Large) [A]	8.0	5.0	9.0			
Output ON-resistance (Normal) (H+L) $[\Omega]$		0.49	0.8	0.33			
Error detection function		TSD, ISD, POR*		TSD, ISD, POR, OPD*			
Package		P-WQFN48-0707-0.50-003		P-VQFN48-0707-0.50-004			

^{*} Thermal shutdown (TSD), over current detection (ISD), power-on-reset (POR), motor load open (OPD)

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